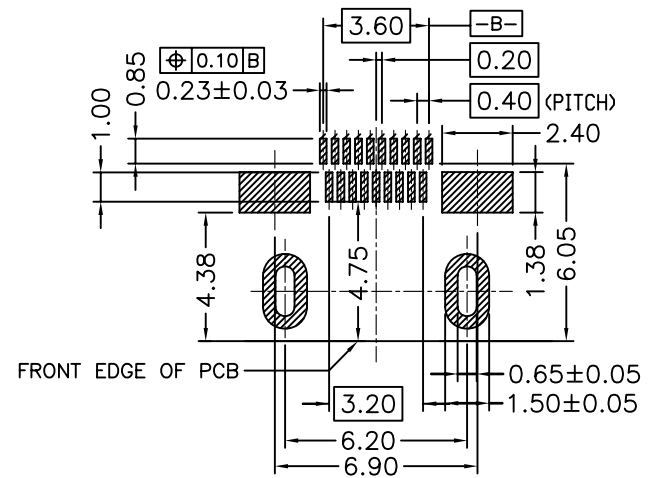
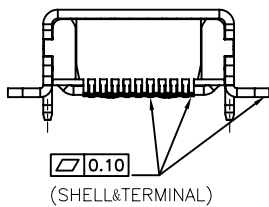
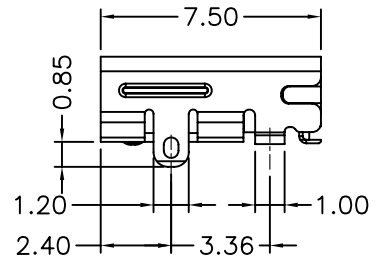
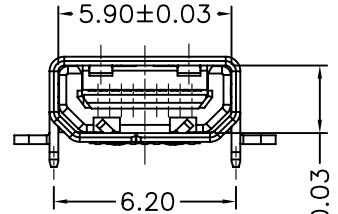


TERMINAL CONTACT AREA PLATING CODE:
 1: CONTACT AREA: GOLD FLASH
 SOLDER AREA: GOLD FLASH
 2: CONTACT AREA: 3u" GOLD
 SOLDER AREA: GOLD FLASH
 A: CONTACT AREA: GOLD FLASH
 SOLDER AREA: MATTE TIN 100u"
 B: CONTACT AREA: 3u" GOLD
 SOLDER AREA: MATTE TIN 100u"

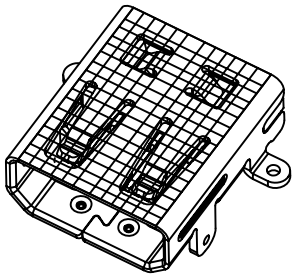
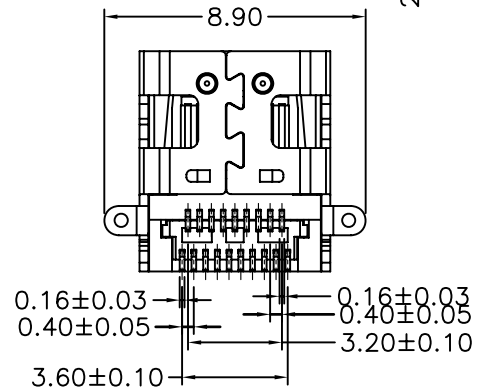
PART NO: HHF-12X000-XSD
 PACKAGING CODE
 1: TARY PACKING
 2: TAPE REEL PACKAGEING
 3: TUBE PACKING
 MYLAR:
 0: WITHOUT MYLAR
 1: WITH MYLAR



RECOMMENDED PCB LAYOUT(.XX±0.05)
 CONNECTOR SIDE(TOP VIEW)



NOTE:
 1.MATERIAL AND FINISH SEE THE TABLE.
 2.MECHANICAL CHARACTERISTICS
 INSERTION FORCE: 44.1N MAX
 EXTROCTION FORCE: 5N MIN(AFTER 5000 CYCLES 3N MIN.), 25N MAX.
 MATING CYCLE:5000 CYCLES
 3.ELECTRICAL CHARACTERISTICS
 RATING CURRENT: 0.5A
 RATING VOLTAGE: 40V
 CONTACT RESISTANCE: 10 MILLOHMS OHMS MAX (EXCLDUING CONDUCTOR RESISTANCE)
 INSULATION RESISTANCE:
 a, UNMATED: 100M OHMS MIN AT 500 VDC
 b, MATED: 10M OHMS MIN AT 150 VDC
 DIELECTRIC WITHSTANDING VOLTAGE:
 250V AC/1MINUTE
 OPERATING TEMPERATURE: -20°C---+85°C
 STORAGE TEMPERATURE: -20°C---+65°C
 4.MARKED ⊗ DIMENSION SHOULD BE MEASURED BY QIP;



MATERIAL	TOLERANCE UNSPECIFIED	ZheJiang HeFeng Technology Co.,Ltd	SCALE	UNIT
	0.0 ±0.30 0° ±2° 0.00 ±0.20 .0° ±1° 0.000 ±0.10 .0° ±0.5°		1:1	mm
FINISH	DRAWN	NAME	SHEET	
	Chu 11/03/02	HDMI D/F TYPE SMT TYPE (HSD Series)	1/2	
	DESIGNER		DRAWING NO.	REV
	Chu 11/03/02			
CHECKED	APPROVED	HHF-1XX000-XSD		

A	新版发行	chu	2011-10-06
Rev. 版本	CHANGE DESCRIPTION 变更内容	REVISOR 制/修订人	DATE 日期